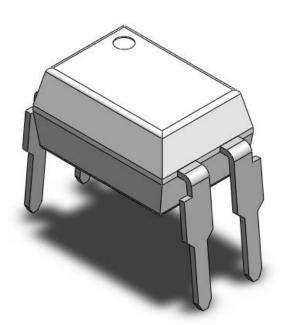


Features

- High isolation 5000 VRMS
- CTR : Min 1000%
- High B_{VCEO} = 350V
- RoHS Compliance
- REACH Compliance
- External Creepage ≥ 7.4mm
- Distance Through Isolation ≥ 0.4mm
- Spatial Distance ≥ 7.5mm (S/SL Type)
- Spatial Distance ≥ 8.0mm (M/SLM Type)
- Regulatory Approvals
 - UL UL1577 (E364000)
 - VDE EN60747-5-5(VDE0884-5)
 - CQC GB4943.1, GB8898
 - IEC60065, IEC60950

Package Outline



Note: Different lead forming options available. See package

dimension.

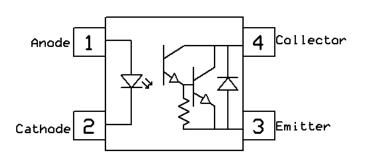
Description

The CT852 consists of a high power photodarlington transistor optically coupled to a gallium arsenide Infrared-emitting diode in a 4-lead DIP package different lead forming options.

Applications

- Switch mode power supplies
- Computer peripheral interface
- Microprocessor system interface







Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units	Notes
Viso	Isolation voltage	5000	Vrms	
T _{OPR}	Operating temperature	-55 ~ +100	°C	
Tstg	Storage temperature	-55 ~ +150	°C	
TSOL	Soldering temperature	260	°C	
Emitter				
lF	Forward current	80	mA	
I _{F(TRANS)}	Peak transient current (≤1µs P.W,300pps)	1	А	
VR	Reverse voltage	6	V	
PD	Power dissipation	150	mW	
Detector				
PD	Power dissipation	300	mW	
BVCEO	Collector-Emitter Breakdown Voltage	350	V	
B _{VECO}	Emitter-Collector Breakdown Voltage	0.1	V	
lc	Collector Current	150	mA	



Electrical Characteristics

T_A = 25°C (unless otherwise specified)

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I⊧=10mA		1.24	1.4	V	
I _R	Reverse Current	$V_R = 5V$	-	-	5	μA	
CIN	Input Capacitance	f= 1MHz	-	45	-	pF	

Detector Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
BVCEO	Collector-Emitter Breakdown	I _C = 100μA	350	-	-	V	
B _{VECO}	Emitter-Collector Breakdown	I _E = 100μA	0.1	-	-	V	
ICEO	Collector-Emitter Dark Current	V _{CE} = 200V, I _F =0mA	-	-	100	nA	

Transfer Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
CTR	Current Transfer Ratio	IF= 1mA, VCE= 2V	1000		15000	%	
V _{CE(SAT)}	Collector-Emitter Saturation Voltage	IF= 20mA, Ic= 100mA	-	-	1.2	V	
Rio	Isolation Resistance	VIO= 500VDC	5x10 ¹⁰			Ω	
Сю	Isolation Capacitance	f= 1MHz		0.6		pF	

Switching Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
tr	Rise Time	1 - 2mA $1/2 - 2/2$ B - 1000	-	-	250	0	
t _f	Fall Time	$I_{C}=2mA$, $V_{CE}=2V$, $R_{L}=100\Omega$	-	-	95	μs	



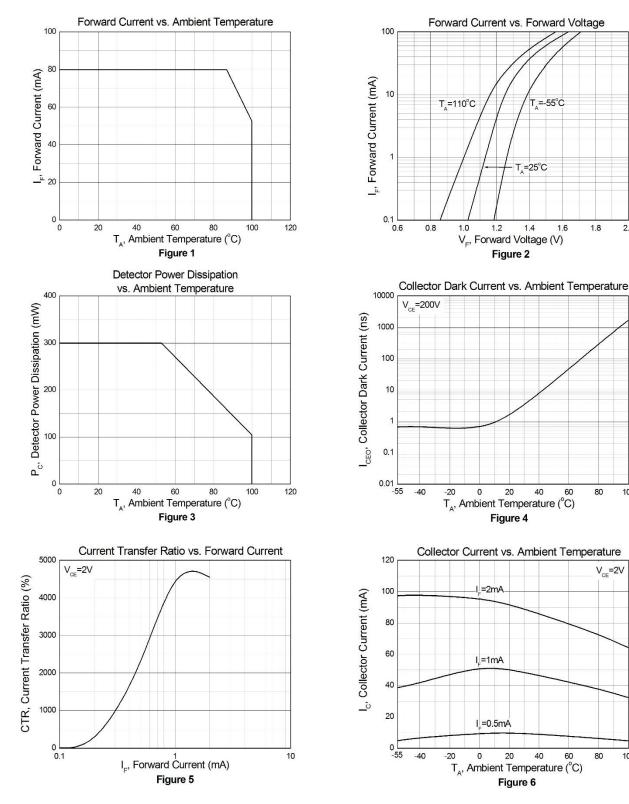
2.0

100

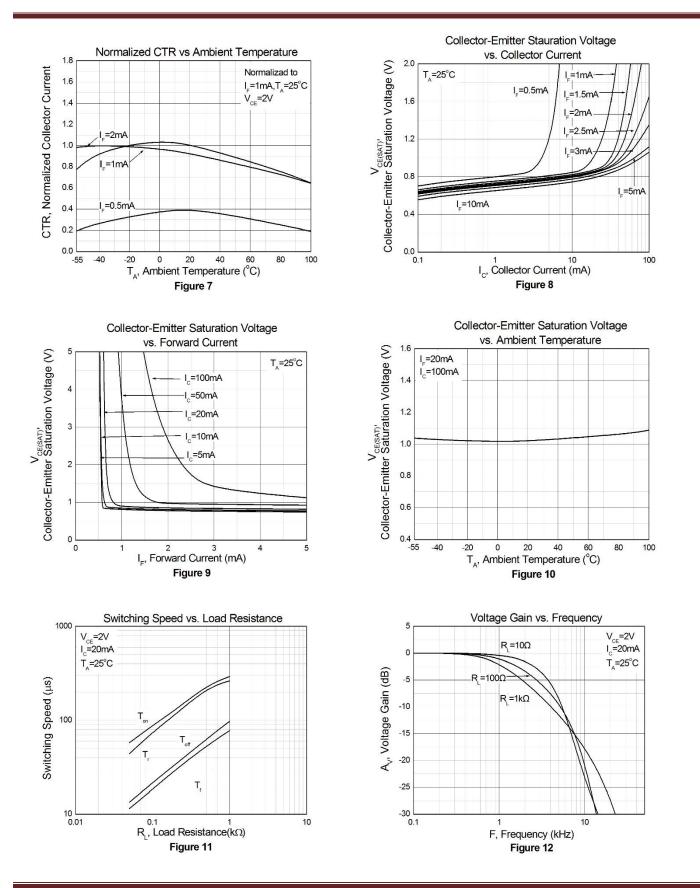
100

DC Input 4-Pin High Power Photodarlington Optocoupler

Typical Characteristic Curves



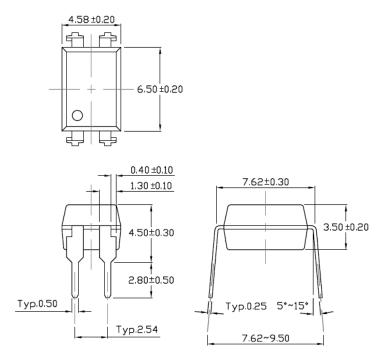




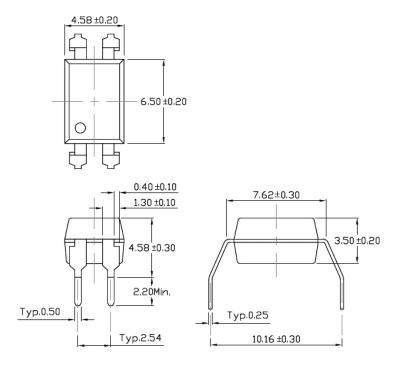


Package Dimension Dimensions in mm unless otherwise stated

Standard DIP – Through Hole

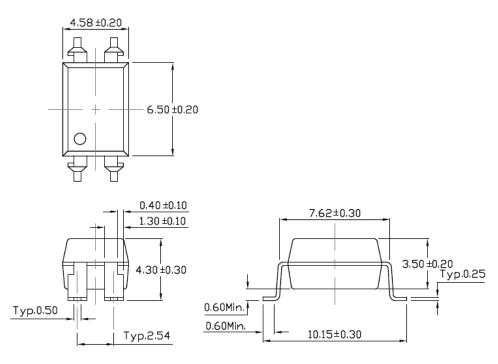


Gullwing (400mil) Lead Forming – Through Hole (M Type)

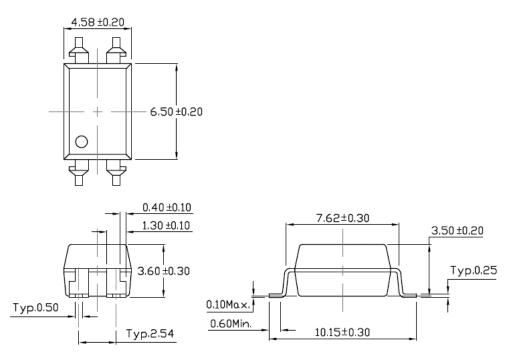




Surface Mount Lead Forming (S Type)

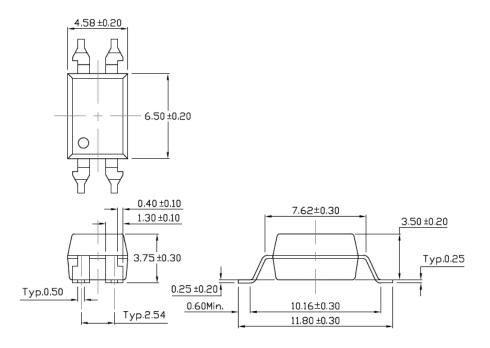


Surface Mount (Low Profile) Lead Forming (SL Type)



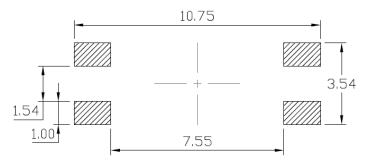


Surface Mount (Gullwing) Lead Forming (SLM Type)

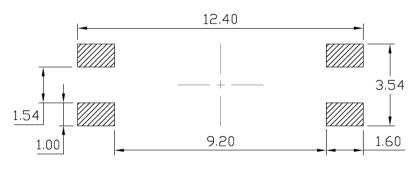


Recommended Solder Mask Dimensions in mm unless otherwise stated

Surface Mount Lead Forming & Surface Mount (Low Profile) Lead Forming

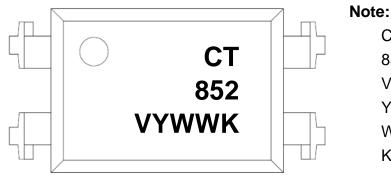


Surface Mount (Gullwing) Lead Forming





Marking Information



ote:	
СТ	: Denotes "CT Micro"
852	: Part Number
V	: VDE Option
Y	: Fiscal Year
WW	: Work Week
K	: Manufacturing Code

Ordering Information

CT852(V)(Y)(Z)-G

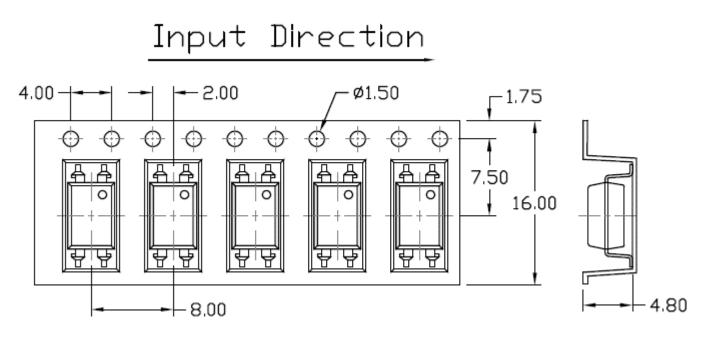
- CT = Denotes "CT Micro"
- 852 = Part Number
- V = VDE Option (V or None)
- Y = Lead form option (S, SL, M, SLM or none)
- Z = Tape and reel option (T1, T2, or none)
- G = Material option (G: Green, None: Non-green)

Option	Description	Quantity
None	Standard 4 Pin Dip	100 Units/Tube
М	Gullwing (400mil) Lead Forming	100 Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1500 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1500 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	1500 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming – With Option 2 Taping	1500 Units/Reel
SLM(T1)	Surface Mount (Gullwing) Lead Forming– With Option 1 Taping	1500 Units/Reel
SLM(T2)	Surface Mount (Gullwing) Lead Forming – With Option 2 Taping	1500 Units/Reel

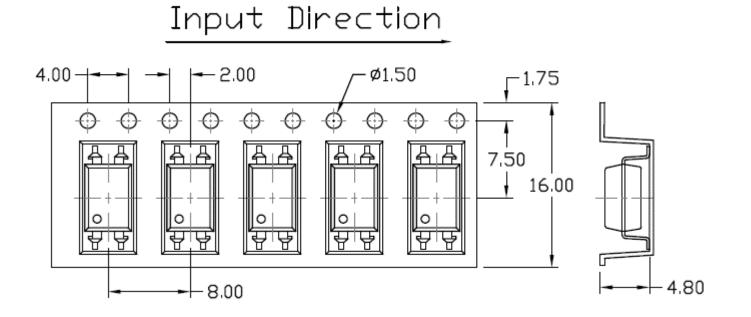


Carrier Tape Specifications Dimensions in mm unless otherwise stated

Option S(T1) & SL(T1)



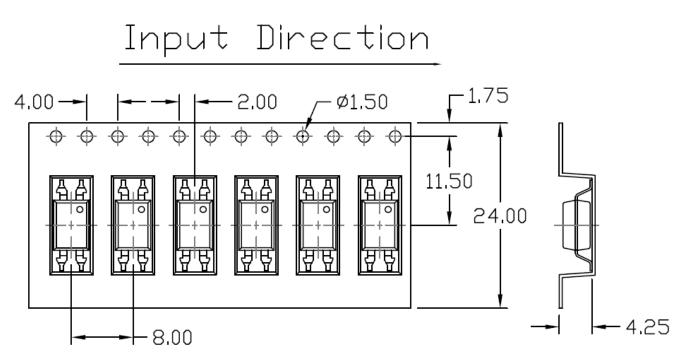
Option S(T2) & SL(T2)



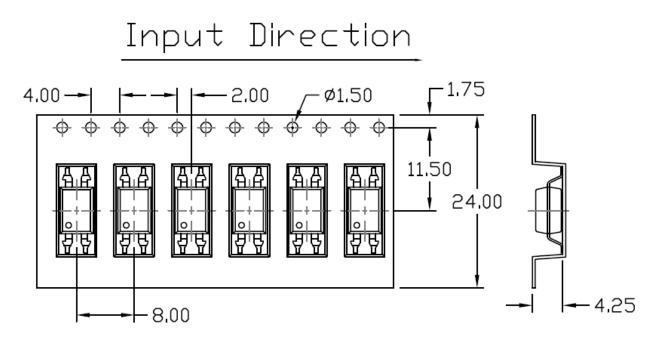




Option SLM(T1)



Option SLM(T2)





Wave soldering (follow the JEDEC standard JESD22-A111)

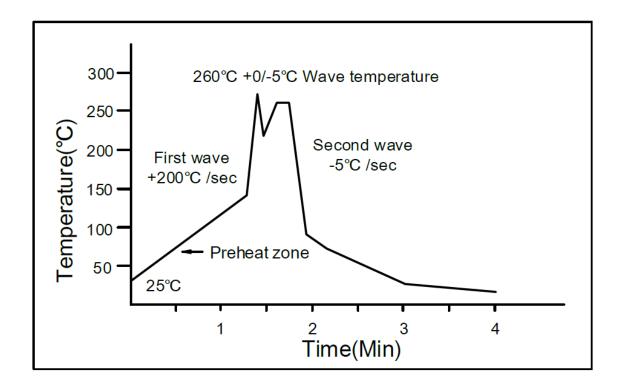
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature:25 to 140°C.

Preheat time: 30 to 80 sec.

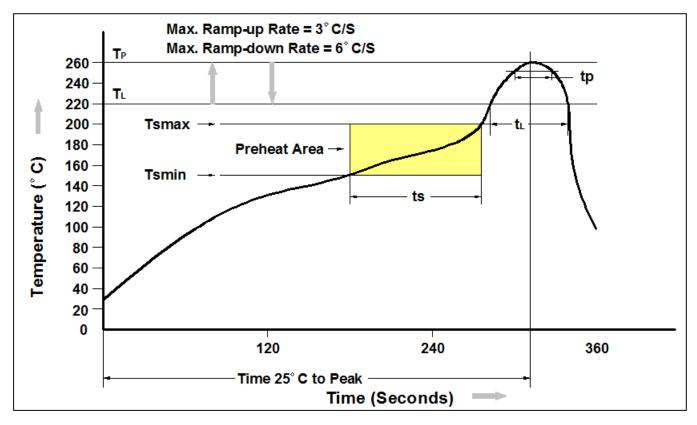


Iron soldering (follow the standard MIL-STD 202G, Method 210F)

Allow single lead soldering in every single process. One time soldering is recommended. Temperature: 350+±10°C Time: 5 sec max.



Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t⊳)	3°C/second max.
Liquidous Temperature (TL)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T_P to T_L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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